Structural Effects of Channel Cross-section on a Gate Capacitance of Silicon Nanowire Field-Effect Transistors



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Event, Venue information

For suppression of off-state leakage current



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Expectation for the increase of gate capacitance





Purpose of this work

✓ To investigate the effects of SiNW cross-sectional shapes on gate capacitance of SiNW FET.

✓To compare the experimental results with the simulation results.

Computer simulation scheme

Cross-sectional shape of SiNW FET in this work



 ✓ The amount of inversion charge was normalized by the peripheral length (the sum of side surfaces and top surface)

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- ✓ Quantum-mechanical effect approximation: Modified Local Density Approximation method.
- ✓ Oxide thickness: Uniform around SiNW channel
- ✓ Calculation of the gate capacitance: $C = \frac{\partial Q}{\partial Q}$

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High inversion carrier density regions around corners because of electric-field concentration



Effects of corner radius on inversion charge density of SiNW nFETs

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Effects of cross-sectional dimensions on Q_{inv} and EOT of SiNW nFETs with rectangular cross-sections



Structural advantage of SiNW nFETs on gate capacitance

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Comparison of simulation result with experimental results



Enhancement of the short channel effect immunity by reduction of oxide thickness





Conclusions

✓ Structural advantage of SiNW FET on the gate capacitance is investigated.

✓ As the cross-sectional dimensions decreased, structural gain of the gate capacitance increased.

✓ EOT advantage was confirmed down to sub-1.5 nm by both simulation and experiments.

✓ SiNW FET is more suitable for improvement of I_{ON}/I_{OFF} characteristics than planar FET with the same oxide thickness with respect to the gate capacitance.

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